

# 2SK1807

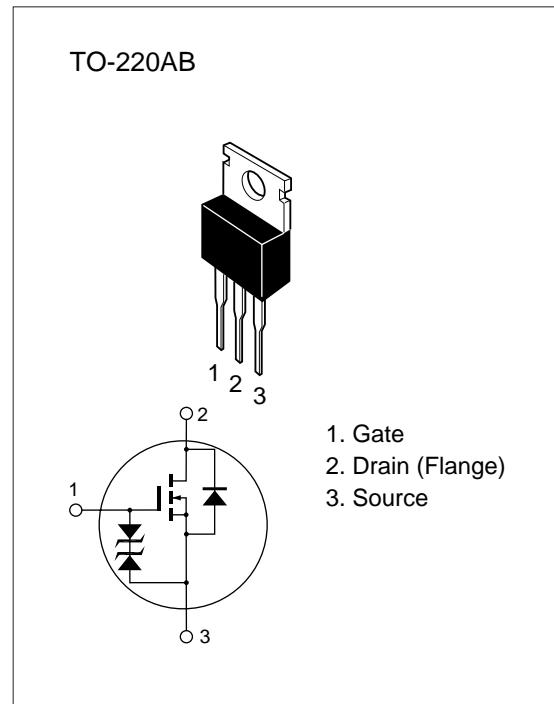
## Silicon N Channel MOS FET

### Application

High speed power switching

### Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switchingregulator, DC-DC converter



**Table 1 Absolute Maximum Ratings (Ta = 25°C)**

| Item                                   | Symbol                  | Ratings     | Unit |
|--|-------------------------|-------------|------|
| Drain to source voltage                | V <sub>DSS</sub>        | 900         | V    |
| Gate to source voltage                 | V <sub>GSS</sub>        | ±30         | V    |
| Drain current                          | I <sub>D</sub>          | 4           | A    |
| Drain peak current                     | I <sub>D(pulse)</sub> * | 10          | A    |
| Body-drain diode reverse drain current | I <sub>DR</sub>         | 4           | A    |
| Channel dissipation                    | P <sub>ch</sub> **      | 60          | W    |
| Channel temperature                    | T <sub>ch</sub>         | 150         | °C   |
| Storage temperature                    | T <sub>stg</sub>        | -55 to +150 | °C   |

\* PW ≤ 10 µs, duty cycle ≤ 1 %

\*\* Value at T<sub>c</sub> = 25 °C

**Table 2 Electrical Characteristics (Ta = 25°C)**

| Item                                       | Symbol               | Min | Typ | Max | Unit | Test Conditions   |
|--|----------------------|-----|-----|-----|------|---|
| Drain to source breakdown voltage          | V <sub>(BR)DSS</sub> | 900 | —   | —   | V    | I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0                                     |
| Gate to source breakdown voltage           | V <sub>(BR)GSS</sub> | ±30 | —   | —   | V    | I <sub>G</sub> = ±100 µA, V <sub>DS</sub> = 0                                   |
| Gate to source leak current                | I <sub>GSS</sub>     | —   | —   | ±10 | µA   | V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0                                    |
| Zero gate voltage drain current            | I <sub>DSS</sub>     | —   | —   | 250 | µA   | V <sub>DS</sub> = 720 V, V <sub>GS</sub> = 0                                    |
| Gate to source cutoff voltage              | V <sub>GS(off)</sub> | 2.0 | —   | 3.0 | V    | I <sub>D</sub> = 1 mA, V <sub>DS</sub> = 10 V                                   |
| Static drain to source on state resistance | R <sub>DS(on)</sub>  | —   | 3.0 | 4.0 | Ω    | I <sub>D</sub> = 2 A<br>V <sub>GS</sub> = 10 V *                                |
| Forward transfer admittance                | y <sub>fs</sub>      | 1.7 | 2.7 | —   | S    | I <sub>D</sub> = 2 A<br>V <sub>DS</sub> = 10 V *                                |
| Input capacitance                          | C <sub>iss</sub>     | —   | 740 | —   | pF   | V <sub>DS</sub> = 10 V  |
| Output capacitance                         | C <sub>oss</sub>     | —   | 305 | —   | pF   | V <sub>GS</sub> = 0   |
| Reverse transfer capacitance               | C <sub>rss</sub>     | —   | 150 | —   | pF   | f = 1 MHz   |
| Turn-on delay time                         | t <sub>d(on)</sub>   | —   | 15  | —   | ns   | I <sub>D</sub> = 2 A  |
| Rise time                                  | t <sub>r</sub>       | —   | 60  | —   | ns   | V <sub>GS</sub> = 10 V  |
| Turn-off delay time                        | t <sub>d(off)</sub>  | —   | 100 | —   | ns   | R <sub>L</sub> = 15 Ω   |
| Fall time                                  | t <sub>f</sub>       | —   | 80  | —   | ns   |   |
| Body-drain diode forward voltage           | V <sub>DF</sub>      | —   | 0.9 | —   | V    | I <sub>F</sub> = 4 A, V <sub>GS</sub> = 0                                       |
| Body-drain diode reverse recovery time     | t <sub>rr</sub>      | —   | 800 | —   | ns   | I <sub>F</sub> = 4 A, V <sub>GS</sub> = 0,<br>dI <sub>F</sub> / dt = 100 A / µs |

\* Pulse Test

See characteristic curves of 2SK1340

